

**IN THE CLAIMS:**

Amend claims 1-2 and 7-9, cancel claims 3-6, and add new claims 10-20 as shown in the following listing of claims, which replaces all previous versions and listings of claims.

1. (currently amended) A semiconductor device comprising: a flexible printed circuit; a semiconductor chip mounted on the flexible printed circuit; having a connection terminal portion comprising that includes a plurality of connection terminal lands arranged on the flexible printed circuit in one of a stepped configuration and a grid configuration; a plurality of wirings connecting the respective connection terminal lands to the semiconductor chip; land-shaped connection terminals arranged in a step form or a grid form and an insulating film disposed on the wirings but not disposed on the connection terminal lands. provided to a wiring connected with the respective land-shaped connection terminals; and a semiconductor chip mounted on the flexible printed circuit.

2. (currently amended) A semiconductor device according to ~~claim 2~~, ~~wherein the land-shaped connection terminals are commonly used as~~ claim 2; wherein the connection terminal lands comprise test terminals for conducting an electrical test.

3. - 6. (canceled).

7. (currently amended) An electronic device comprising: a flexible printed circuit; a semiconductor chip mounted on the flexible printed circuit; having a connection terminal portion comprising that includes a plurality of connection terminal lands arranged on the flexible printed circuit in one of a stepped configuration and a grid configuration; a plurality of wirings connecting the respective connection terminal lands to the semiconductor chip; that includes a plurality of connection terminal lands arranged in a step form or a grid form and an insulating film disposed on the wirings; and provided to a wiring connected with the respective connection terminal lands; a semiconductor chip mounted on the flexible printed circuit; and an electronic part connected to the connection terminal portion for receiving operated at a time when an output signal from the semiconductor chip is inputted through the plurality of connection terminal lands.

8. (currently amended) An electronic device according to ~~claim 7, wherein~~ claim 7; wherein the electronic part comprises ~~a terminal portion provided in a region connected with the flexible printed circuit, and the terminal portion comprises a plurality of terminals connected to the flexible printed circuit provided at positions opposed to~~

positions at which the connection terminal lands are arranged.  
~~of the flexible printed circuit and a plurality of wirings~~  
~~which are connected with the terminals and covered with an~~  
~~insulating film.~~

9. (currently amended) An electronic device  
according to ~~elaim 7~~, wherein claim 7; wherein the electronic  
part ~~is~~ comprises a display panel having a display screen.

10. (new) A semiconductor device comprising:  
a flexible printed circuit;  
a semiconductor chip mounted on the flexible printed  
circuit;  
a plurality of rows and columns of connection  
terminal lands arranged on the flexible printed circuit;  
a plurality of wirings connecting the respective  
connection terminal lands to the semiconductor chip; and  
an insulating film disposed on the wirings but not  
disposed on the connection terminal lands.

11. (new) A semiconductor device according to claim  
10; wherein the connection terminal lands comprise test  
terminals for conducting an electrical test.

12. (new) A semiconductor device according to claim  
10; wherein the insulating film comprises an organic  
insulating film.

13. (new) A semiconductor device according to claim 10; wherein the connection terminal lands within each of the columns of connection terminal lands are arranged in a stepped configuration.

14. (new) An electronic device comprising: a semiconductor device according to claim 10; and an electronic part for receiving an output signal from the semiconductor chip through the connection terminal lands of the semiconductor device.

15. (new) An electronic device according to claim 14; wherein the electronic part comprises a plurality of terminals connected to the flexible printed circuit at positions opposed to positions at which the connection terminal lands are arranged.

16. (new) An electronic device according to claim 14; wherein the electronic part comprises a display panel having a display screen.

17. (new) An electronic device according to claim 14; wherein the connection terminal lands comprise test terminals for conducting an electrical test.

18. (new) An electronic device according to claim 14; wherein the insulating film comprises an organic insulating film.

19. (new) An electronic device according to claim 14; wherein the connection terminal lands within each of the columns of connection terminal lands are arranged in a stepped configuration.

20. (new) An electronic device according to claim 19; wherein each of the columns of connection terminal lands comprises five connection terminal lands spaced apart from one another at a distance of approximately 54  $\mu\text{m}$ .